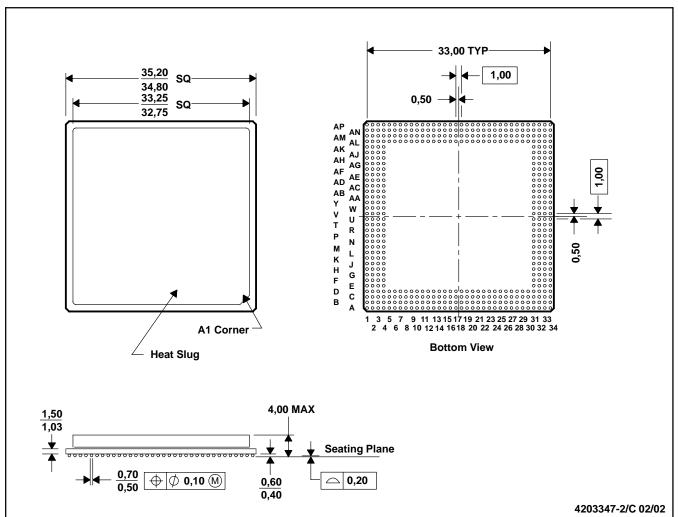
MECHANICAL DATA

MPBG201A - OCTOBER 2001 - REVISED FEBRUARY 2002

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Flip chip application only.

GPN (S-PBGA-N480)



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